

Application No.: 10/776,227**Docket No.: 4459-139****ABSTRACT**

A semiconductor package ~~comprises~~ includes spacers, a chip, bonding wires, contacts, and an encapsulant. The chip is disposed on the spacers. The bonding wires are electrically connected to the chip, and the contacts are electrically connected to the bonding wires. The contacts are electrically connected to an external circuit board. The encapsulant encapsulates the spacers and the active and back surfaces of the chip so as to lower the thermal stress of the chip.